



US 20240180039A1

(19) **United States**

(12) **Patent Application Publication**
SEO et al.

(10) **Pub. No.: US 2024/0180039 A1**

(43) **Pub. Date:** **May 30, 2024**

(54) **METHOD OF MANUFACTURING
MULTILAYER PIEZOELECTRIC ELEMENT
INCLUDING INTERNAL ELECTRODES**

H10N 30/067 (2006.01)
H10N 30/50 (2006.01)
H10N 30/87 (2006.01)

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(52) **U.S. Cl.**
CPC *H10N 30/053* (2023.02); *C22C 9/06*
(2013.01); *H10N 30/067* (2023.02); *H10N*
30/50 (2023.02); *H10N 30/871* (2023.02);
H10N 30/877 (2023.02)

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(57) **ABSTRACT**

Disclosed is a method of manufacturing a multilayer piezo-
electric element including internal electrodes, including
providing a piezoelectric sheet including ceramic, forming
internal electrodes on the piezoelectric sheet to create a
piezoelectric sheet with internal electrodes formed thereon,
stacking a plurality of piezoelectric sheets with internal
electrodes formed thereon to create a piezoelectric stack,
sintering the piezoelectric stack to create a sintered piezo-
electric stack, and heat-treating the sintered piezoelectric
stack in a reducing atmosphere, in which the internal elec-
trodes are formed in an area ratio of 90% or more relative to
the area of the piezoelectric sheet, thereby facilitating reduc-
tion of the internal electrodes even by reduction heat treat-
ment at a relatively low temperature.

(21) Appl. No.: **18/521,287**

(22) Filed: **Nov. 28, 2023**

(30) **Foreign Application Priority Data**

Nov. 29, 2022 (KR) 10-2022-0163185

Publication Classification

(51) **Int. Cl.**
H10N 30/053 (2006.01)
C22C 9/06 (2006.01)

